



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



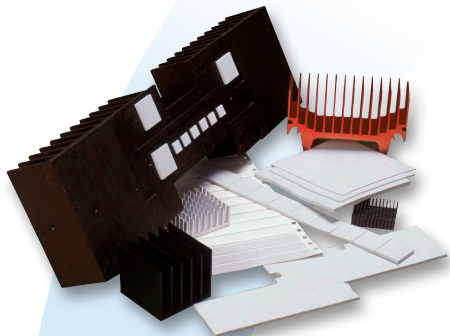
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





SOFT, FREESTANDING GAP FILLER

Tflex™ 200 V0 is a very soft, freestanding gap filler that is more compliant than most other gap fillers. Combining good thermal conductivity of 1.1 W/mK with high conformability, this gap filler produces low thermal resistance. The alumina filler allows the product to remain a cost effective solution where moderate thermal performance is acceptable.

Naturally tacky and not requiring additional adhesive coating, the Tflex™ 200 V0 can inhibit thermal performance. This gap filler is both electrically insulating and stable from -40°C to 160°C and meets UL 94 V0 rating.

FEATURES AND BENEFITS

- Soft and compressible for low stress applications
- Naturally tacky needing no further adhesive coating
- 1.1 W/mK thermal conductivity
- Available in thicknesses from 0.010" (0.25mm) to 0.200" (5.0mm)

APPLICATIONS

- Cooling components to the chassis or frame
- High speed mass storage drives
- RDRAM memory modules
- Heat pipe thermal solutions
- Automotive engine control units
- Wireless communication hardware

global solutions: local support.™

Americas: +1.800.843.4556

Europe: +49.8031.2460.0

Asia: +86.755.2714.1166

CLV-customerservice@lairdtech.com

www.lairdtech.com/thermal

	Tflex™ 220 V0	Tflex™ 240 V0	Tflex™ 260 V0	Tflex™ 280 V0	Tflex™ 2100 V0	TEST METHOD
Construction & Composition	Reinforced ceramic filled silicone elastomer	Ceramic filled silicone elastomer	Ceramic filled silicone elastomer	Ceramic filled silicone elastomer	Ceramic filled silicone elastomer	
Color	Light Gray	Light Gray	Light Gray	Light Gray	Light Gray	Visual
Thickness	0.02" (0.508mm)	0.04" (1.016mm)	0.06" (1.524mm)	0.08" (2.032mm)	0.10" (2.54mm)	
Thickness Tolerance	± 0.002" (± 0.05mm)	± 0.004" (± 0.10mm)	± 0.006" (± 0.15mm)	± 0.008" (± 0.20mm)	± 0.010" (± 0.25mm)	
Density	1.75 g/cm ³	1.73 g/cm ³	1.73 g/cm ³	1.73 g/cm ³	1.73 g/cm ³	Helium Pycnometer
Hardness	50 Shore 00	45 Shore 00	45 Shore 00	45 Shore 00	45 Shore 00	ASTM D2240
Tensile Strength	464 psi	48 psi	48 psi	48 psi	48 psi	ASTM D412
% Elongation	10.5	63.0	60.6	60.6	60.6	ASTM D412
Outgassing TML (Post Cured)	0.34%	0.34%	0.34%	0.34%	0.34%	ASTM E595
Outgassing CVCM (Post Cured)	0.10%	0.10%	0.10%	0.10%	0.10%	ASTM E595
UL Flammability Rating	94 V0	94 V0	94 V0	94 V0	94 V0	E180840
Temperature Range	-45°C to 160°C	-45°C to 160°C	-45°C to 160°C	-45°C to 160°C	-45°C to 160°C	
Thermal Conductivity	1.1 W/mK	1.1 W/mK	1.1 W/mK	1.1 W/mK	1.1 W/mK	ASTM D5470 (modified)
Total Thermal Resistance @ 10 psi @ 69KPa	0.80 °C-in ² /W 5.13 °C-cm ² /W	1.57 °C-in ² /W 10.13 °C-cm ² /W	2.05 °C-in ² /W 13.23 °C-cm ² /W	2.51 °C-in ² /W 16.19 °C-cm ² /W	2.93 °C-in ² /W 18.90 °C-cm ² /W	ASTM D5470 (modified)
Coefficient of Thermal Expansion	229 ppm/°C 35°C to 130°C	229 ppm/°C 35°C to 130°C	229 ppm/°C 35°C to 130°C	229 ppm/°C 35°C to 130°C	229 ppm/°C 35°C to 130°C	IPC-TM-650 2.4.24
Breakdown Voltage	12,000 Volts AC	>27,000 Volts	>27,000 Volts	>27,000 Volts	>27,000 Volts	ASTM D149
Volume Resistivity	4 x 10 ¹³ ohm-cm	4 x 10 ¹³ ohm-cm	4 x 10 ¹³ ohm-cm	4 x 10 ¹³ ohm-cm	4 x 10 ¹³ ohm-cm	ASTM D257
Dielectric Constant @ 1MHz	5.5	5.5	5.5	5.5	5.5	

STANDARD THICKNESSES

0.020" (0.51mm)	0.030" (0.76mm)	0.040" (1.02mm)	0.050" (1.27mm)
0.060" (1.52mm)	0.070" (1.78mm)	0.080" (2.03mm)	0.090" (2.29mm)
0.100" (2.54mm)	0.110" (2.79mm)	0.120" (3.05mm)	0.130" (3.30mm)
0.140" (3.56mm)	0.150" (3.81mm)	0.160" (4.06mm)	0.170" (4.32mm)
0.180" (4.57mm)	0.190" (4.83mm)	0.200" (5.08mm)	

Consult the factory for alternate thicknesses

STANDARD SHEET SIZES

9" x 9" (229mm x 229mm) Tflex™ 200V0 may be die cut into individual shapes. Pressure sensitive adhesive is not applicable for Tflex™ products.

REINFORCEMENT

0.020" (0.51mm) and 0.030" (0.762mm) are fiberglass reinforced.

Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.

THR-DS-Tflex-200V0 0710

Any information furnished by Laird Technologies, Inc. and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird Technologies materials rests with the end user, since Laird Technologies and its agents cannot be aware of all potential uses. Laird Technologies makes no warranties as to the fitness, merchantability or suitability of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies Terms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2010 Laird Technologies, Inc. All Rights Reserved. Laird, Laird Technologies, the Laird Technologies Logo, and other marks are trade marks or registered trade marks of Laird Technologies, Inc. or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird Technologies or any third party intellectual property rights. A14175-00 Rev. G, 08/13/08